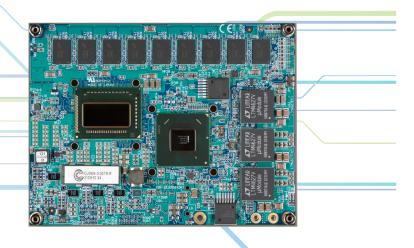
Rugged Com Express with 2nd Generation Intel[®] Core[™]

CPU-162-14

- Intel® Core™i7 and Core™i5
- Rugged:
 - Extended operating temperature
 - Direct mounted CPU and RAM
- Three video ports
- Wind River Linux and Windows



FEATURES

High Performance – Dual and quad core Core i5 and Core i7 for great performance to power ratio

Rugged – Direct-mounted SDRAM memory and CPU, ensuring extremely stable operation; ECC RAM support for extra reliability

Extended Temperature Range – Suitable for -40° to +85°C operation

Feature Rich – SATA, USB, Gigabit Ethernet, Video, PCI and PCI Express

Compact design – COM Express Basic Module size (125mm x 95mm)

Operating Systems – Windows $\mbox{$\mathbb{R}$}$ 7, Windows $\mbox{$\mathbb{R}$}$ Embedded Standard 7 and Wind River Linux

- Defense
- Homeland Security
- Aerospace
- Industrial
- Transportation

The CPU-162-14 is a COM Express module that delivers incredible performance and power efficiency: it supports dual and quad core 2nd Generation Intel® Core™ CPUs, providing the right power/performance profile for any application.

Designed for maximum reliability, the CPU-162-14 supports up to 8GB ECC memory, with memory and CPU soldered directly on the board to provide superior resilience to mechanical stress and vibrations.

With a Basic Module form factor, the CPU-162-14 packs a large number of peripherals in a very compact design: Gigabit Ethernet, four SATA, eight USB, three video ports, x16, x4 and two x1 PCI Express and PCI.

The CPU-162-14 simplifies programming and development with support for Window® 7, Windows® Embedded Standard 7 and Wind River Linux.





System Architecture

Specifications

Rugged Com Express with 2nd Generation Intel[®] Core[™]



PROCESSOR	 Intel® Core™ i7-2715QE / 2.1GHz, 45W
	• Intel® Core™ i7-2655LE / 2.2GHz, 25W
	• Intel® Core™ i7-2610UE / 1.5GHz, 17W
	• Intel® Core™ i5-2515E / 2.5GHz, 35W
	Chipset: Mobile Intel®QM67
MEMORY	Direct-mounted DDR3-1333 SDRAM up to 8GB, ECC supported
	• Factory option configurations: 1GB/2GB/4GB/8GB
	• Dual channel (1GB supports single channel only)
	Boot ROM: SPI-FLASH 8MB
COM EXPRESS	PICMG COM.0 COM Express Module Base Specification Rev 1.0
	Basic Module size (125mm x 95mm)
	Type 2 Pin layout (SDVO replaces PATA)
SYSTEM I/O	 PCI Express 2.0: X16 1 port (X8 2 ports available as factory option), X4 1 port (X1 4 ports available as factory option), X1 2 ports
	 Graphics: Analog VGA / SDVO / LVDS 1 port each
	• 2X SATA-600 + 2X SATA-300
	• 8X USB 2.0
	• 1X ETHERNET 10/100/1000BASE-T
	• 1X PCI(32BIT, 33MHZ, 3.3V)
	• 1X LPC
	• 1x SMBUS
	• 1x I2C BUS
	• 4x GPI + 4X GPO
POWER	• Supply voltage:
	DC 12V (VCC_12V) 12.0V, ±5%, max 13.4A
	DC 5V (VCC_5VSBY) 5.0V, ±5%, max 0.8A
	DC 3V (VCC_RTC) 3.0V, max 6uA
MECHANICAL	• 125mm (W) x 95mm (L) x 21mm (H)
	(incl. 8mm height for heat spreader and spacers)
	 Heat sink is optionally available Waight: 285a
ENVIRONMENTAL	• Weight: 285g • -40° to +85°C
	Humidity: up to 80%RH (no condensation)
	- manually. up to oppoint (no condensation)

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